

IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE

PATENT

Applicant(s):	Misuo Sugiyama; Hatsuyuki Arai	Docket No.:	30598.0004
Reissue of Patent No.:	5,605,499	Application No.:	08/960,431
Issue Date:	February 25, 1997	Filing Date:	October 29, 1997
Title:	FLATTENING METHOD AND FLATTENING APPARATUS OF A SEMICONDUCTOR DEVICE	Examiner:	George Binh Minh Nguyen

SUPPLEMENTAL REISSUE DECLARATION
OF MISUO SUGIYAMA (37 CFR 1.175)

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED
JUL 19 2004
TECHNOLOGY CENTER

Dear Sir/Madam:

I, **MISUO SUGIYAMA**, hereby declare as follows:

1. My residence, post office address and citizenship are as stated below next to my name.
2. I believe that I am an original, first, and joint inventor of the invention described and claimed in U.S. Patent No. 5,605,499 which issued on February 25, 1997, in the Reissue Application Serial No. 08/960,431 filed October 29, 1997.
3. I declare that every error in the patent which was corrected in the present reissue application, and is not covered by any prior Declaration submitted in this application, arose without any deceptive intent on the part of Applicants.
4. I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the

Application Serial No. 08/960,431

United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signature:

Misuo Sugiyama

MISUO SUGIYAMA

Date:

JUN. 23, 2004

Citizenship:

JAPAN

City of Residence:

Hadano-city

Country of Residence: JAPAN

Post Office Address: 660-1, Higashi-Tawara, Hadano-city, Kanagawa-pref., 257-0028, JAPAN

Please send all further correspondence to Snell & Wilmer L.L.P. at the following address:

SNELL & WILMER L.L.P.

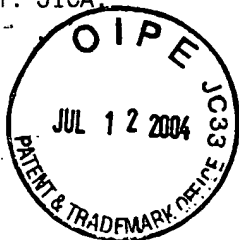
One Arizona Center

Phoenix, Arizona 85004-2202

ATTENTION: Damon L. Boyd

Tel. (602) 382-6337

Fax (602) 382-6070



IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE

PATENT

Applicant(s):	Misuo Sugiyama; Hatsuyuki Arai	Docket No.:	30598.0004
Reissue of Patent No.:	5,605,499	Application No.:	08/960,431
Issue Date:	February 25, 1997	Filing Date:	October 29, 1997
Title:	FLATTENING METHOD AND FLATTENING APPARATUS OF A SEMICONDUCTOR DEVICE	Examiner:	George Binh Minh Nguyen

SUPPLEMENTAL REISSUE DECLARATION
OF HATSUYUKI ARAI (37 CFR 1.175)

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA22313-1450

RECEIVED
JUL 19 2004
TECHNOLOGY CENTER

Dear Sir/Madam:

I, **HATSUYUKI ARAI**, hereby declare as follows:

1. My residence, post office address and citizenship are as stated below next to my name.
2. I believe that I am an original, first, and joint inventor of the invention described and claimed in U.S. Patent No. 5,605,499 which issued on February 25, 1997, in the Reissue Application Serial No. 08/960,431 filed October 29, 1997.
3. I declare that every error in the patent which was corrected in the present reissue application, and is not covered by any prior Declaration submitted in this application, arose without any deceptive intent on the part of Applicants.
4. I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the

Application Serial No. 08/960,431

United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signature: Hatsuyuki Arai
HATSUYUKI ARAI
Date: MAY 26, 2004
Citizenship: JAPAN
City of Residence: Tashkent
Country of Residence: UZBEKISTAN
Post Office Address: JICA Uzbekistan Office, 5th floor, International Business Center, 107-B,
Amir Temur str., Tashkent 700084, UZBEKISTAN

Please send all further correspondence to Snell & Wilmer L.L.P. at the following
address:

SNELL & WILMER L.L.P.
One Arizona Center
Phoenix, Arizona 85004-2202
ATTENTION: Damon L. Boyd

Tel. (602) 382-6337
Fax (602) 382-6070